


MATERIAL DECLARATION SHEET



Package Type	PTVS2-(043C-058C)-H			
Product Line	Semiconductor Products			
Compliance Date	10 th March 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.1745	Amorphous Silica	60676-86-0	87.000	44.43924	46.06
				Solid Epoxy Resin 1	Proprietary	4.600	0.14980	
				Solid Epoxy Resin 2	Proprietary	4.490	0.12771	
				Phenol Resin	Proprietary	2.700	0.75363	
				Carbon Black	1333-86-4	0.700	0.27680	
				Crystalline Silica	14808-60-7	0.510	0.30843	
2	Leadframe	Copper Alloy	0.0618	Copper	7440-50-8	97.433	15.95202	16.31
				Iron	7439-89-6	2.350	0.33812	
				Phosphorus	7723-14-0	0.125	0.00534	
				Zinc	7440-66-6	0.082	0.01076	
				Lead	7439-92-1	0.010	0.00207	
3	Electrodes	Copper Alloy	0.0453	Copper	7440-50-8	95.485	11.30384	11.96
				Silver	7440-22-4	4.500	0.65402	
				Iron	7439-89-6	0.005	0.00052	
				Lead	7439-92-1	0.005	0.00075	
				Zinc	7440-66-6	0.003	0.00028	
4	Clip	Copper Alloy	0.0340	Phosphorous	7723-14-0	0.002	0.00006	8.97
				Copper	7440-50-8	95.485	8.48160	
				Silver	7440-22-4	4.500	0.49073	
				Iron	7439-89-6	0.005	0.00039	
				Lead	7439-92-1	0.005	0.00056	
5	Chip	Silicon	0.0335	Zinc	7440-66-6	0.003	0.00021	8.83
				Phosphorous	7723-14-0	0.002	0.00005	
				Silicon	7440-21-3	90.650	8.00751	
				Nickel	7440-02-0	5.403	0.47730	
				Aluminum	7429-90-5	3.815	0.33699	
6	Solder Paste	Solder	0.0270	Gold	7440-57-5	0.132	0.01163	7.12
				Lead*	7439-92-1	92.500	6.71149	
				Tin	7440-31-5	5.000	0.23129	
7	Terminal Finish	Tin	0.0028	Silver	7440-22-4	2.500	0.17426	0.75
				Tin	7440-31-5	100.000	0.75260	
		Total weight	0.3789					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)